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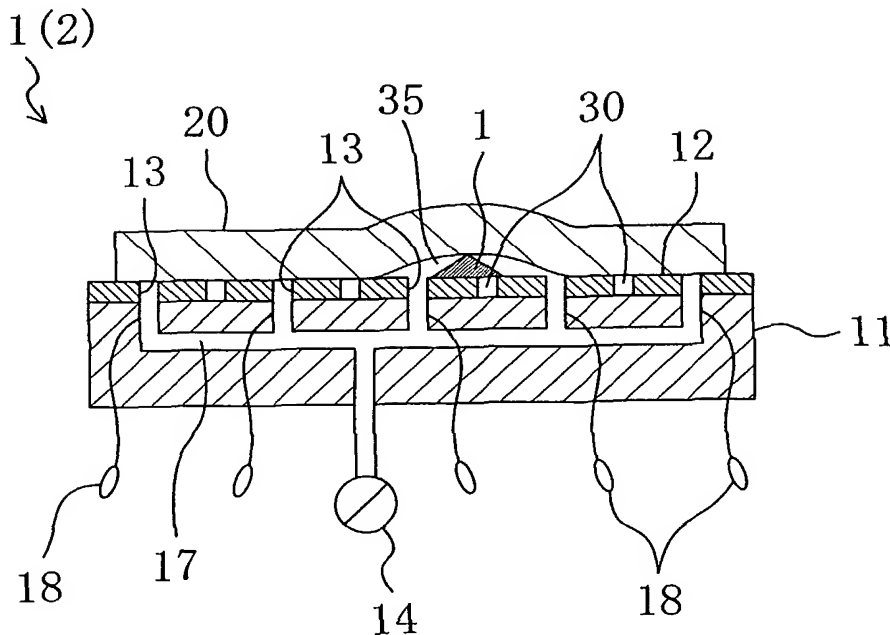
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(54) Title: SUBSTRATE ADSORPTION DEVICE AND SUBSTRATE BONDING DEVICE



(57) Abstract: A substrate
adsorption device 1 includes: a
stage 11 having an adsorption
face 12 for holding a substrate
20; a plurality of adsorption
ports 13 formed in a region of
the adsorption face 12 of the
stage 11; and a vacuum pump 14
connected to each adsorption port
through an air discharge path 17.
A pressure sensor 18 for detecting
the pressure in the air discharge
path 17 is provided, and a plurality
of leak trenches 30 open to both
the adsorption face 12 of the
stage 11 and a side face of the
stage 11 are formed in a region
of the stage 11 except the region
where the adsorption ports 13 are
formed. With such a low-cost and
simple structure, a foreign matter
15, which is a factor of inviting
damage to the substrate 20, is
detected, to prevent damage to the
substrate 20.

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